



Docket No.: M4065.0196/P196
(PATENT)

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Shane P. Leiphart

Application No.: 09/371,955

Group Art Unit: 2811

Filed: August 11, 1999

Examiner: D. Kang

For: ENHANCED BARRIER LINER
FORMATION FOR VIAS

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AMENDMENT UNDER 37 CFR 1.116

Box AF
Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated July 17, 2002 (Paper No. 15), finally rejecting claims 26-40, please amend the above-identified U.S. Patent application as follows:

In the Claims:

Please replace the claims with the respective amended claims below.

26. (Four Times Amended) A semiconductor device, comprising:

a metallic layer over a substrate;

a dielectric layer over said metallic layer;

a via hole extending through the dielectric layer to a surface of the metallic layer;